

TO Quanta Computer Inc.

SPECIFICATION FOR APPROVAL

DESCRIPTION: CONNECTOR

CUSTOMER PROD. NO/DWG. NO: DFTJ34FR009

HON HAI PROD. NO: JFM38A1A-0135-4N

APPROVAL SHEET NO: 2005/3/18

HON HAI DWG. NO./DOCUMENT: DRAWING REV:
SPEC

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL" WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES			

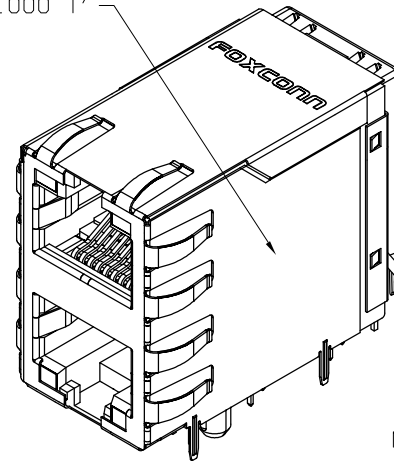
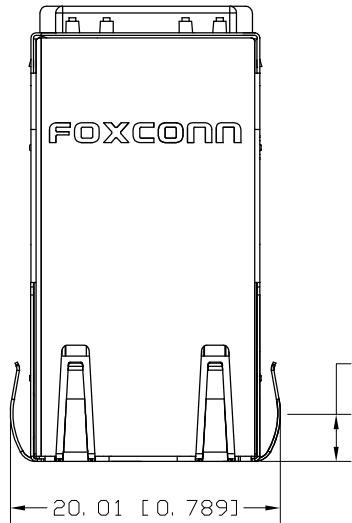


Hon Hai Precision Industry Co., Ltd.

AUTOCAD GENERATED DRAWING, DON'T CHANGE BY HAND

REV.	ECN. NO.	APPD.
X1		L.C WU

MARK PART # AND '1000 T'

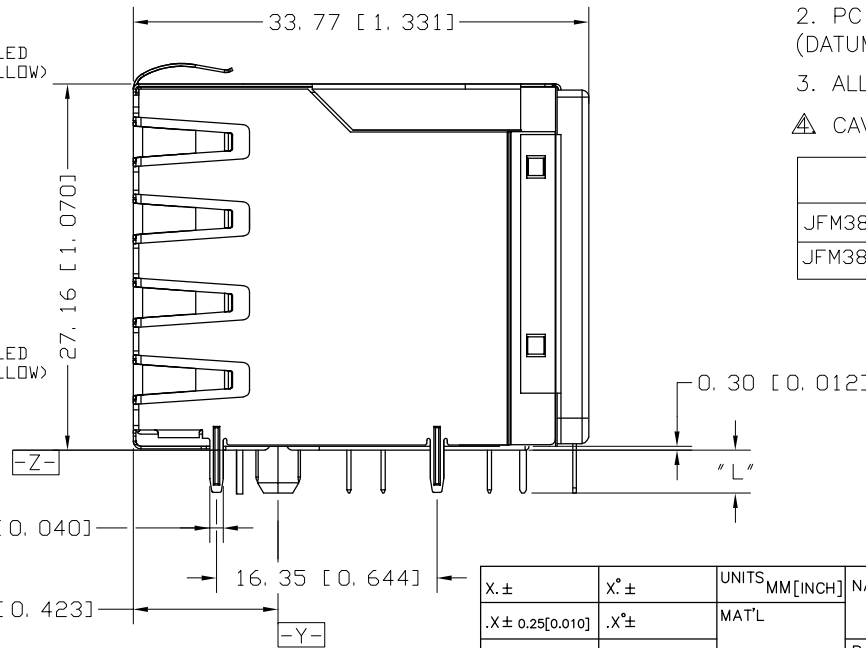
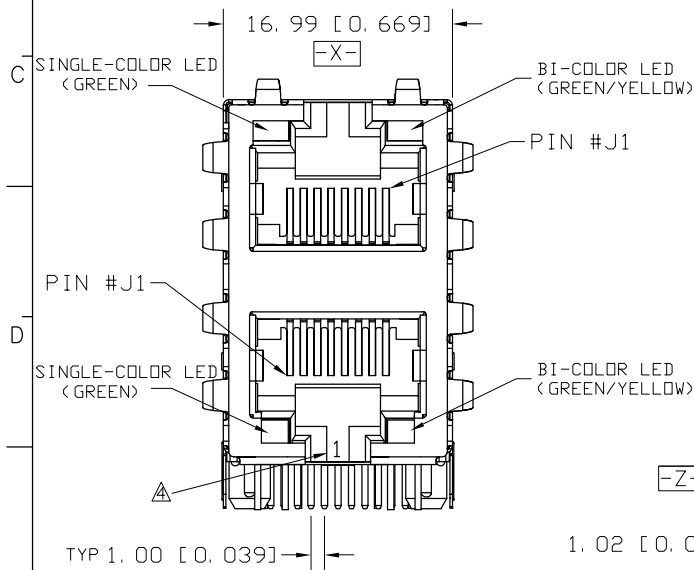


NOTES:

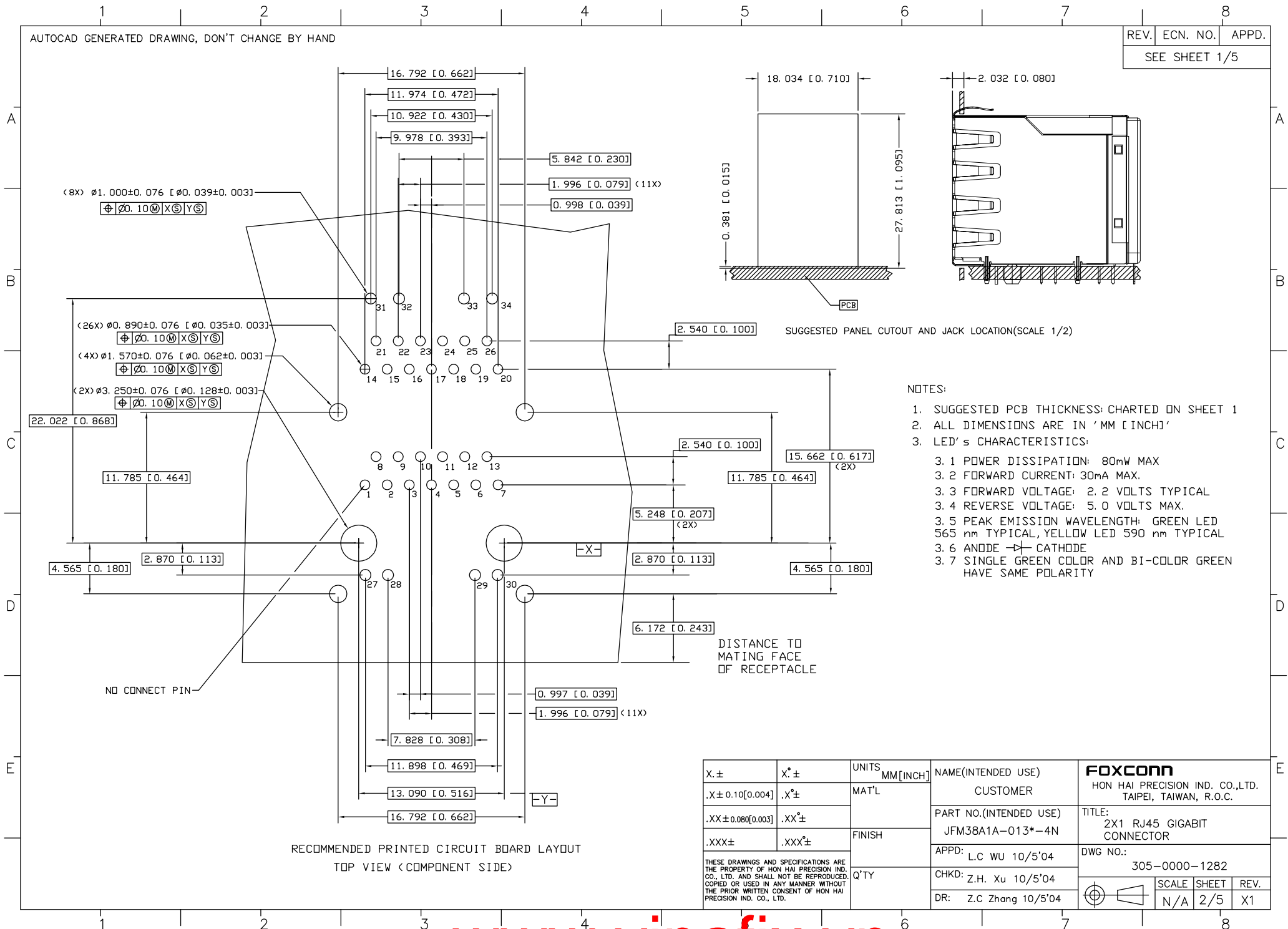
- CONNECTOR TO COMPLY WITH CFR TELECOMMUNICATION STANDARD PART 68 SUBPART F
- PC BOARD SURFACES (STAND OFF) PLANE (DATUM -Z-)
- ALL DIMENSIONS ARE IN "MM [INCH]"

△ CAVITY NO.

P/N	DIM "L"	PCB THICKNESS
JFM38A1A-0135-4N	3.18[0.125]	2.36[0.093]
JFM38A1A-0136-4N	2.16[0.085]	1.57[0.0618]



X.±	X°.±	UNITS	MM[INCH]	NAME(INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.
.X±0.25[0.010]	.X°.±	MAT'L		CUSTOMER	
.XX±0.25[0.010]	.XX°.±			PART NO.(INTENDED USE)	TITLE:
.XXX±	.XXX°.±	FINISH		JFM38A1A-013*-4N	2X1 RJ45 GIGABIT CONNECTOR
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				L.C WU 10/5'04	305-0000-1282
Q'TY	CHKD:	Z.H. Xu 10/5'04	DR:	Z.C Zhang 10/5'04	SCALE SHEET REV.
					NONE 1/5 X1

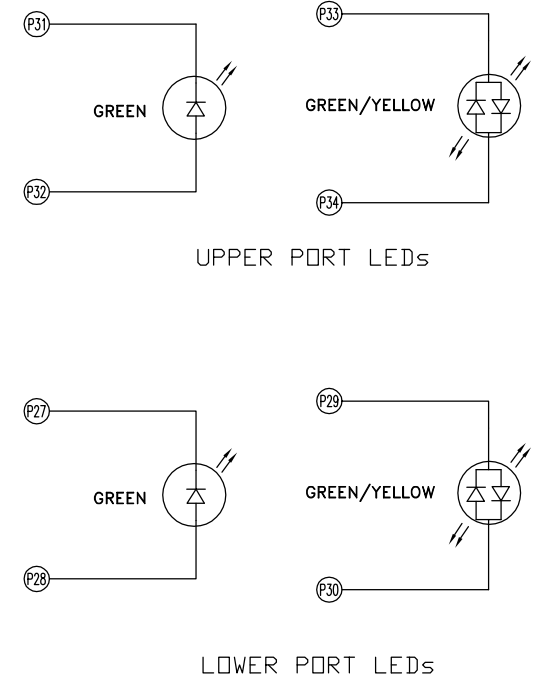
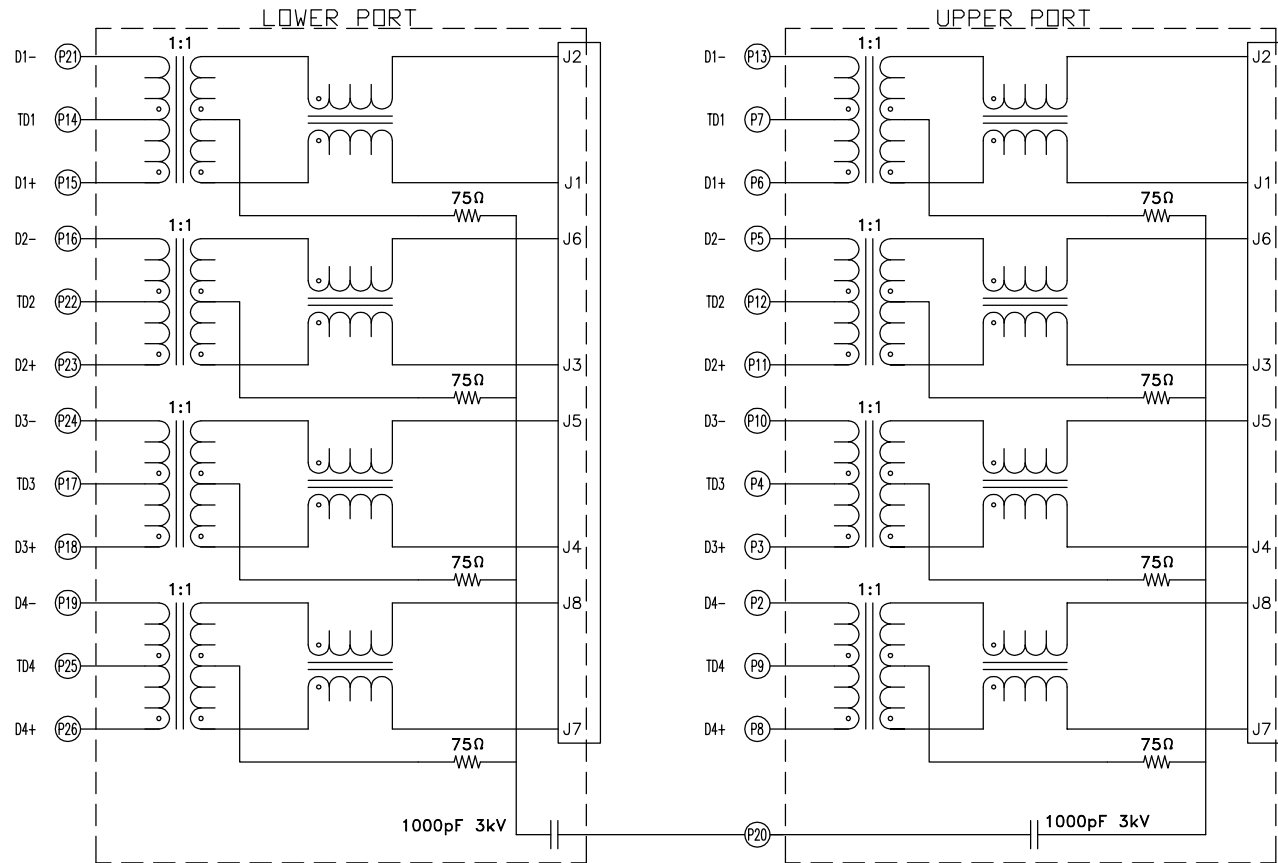


NOTES:

1. SUGGESTED PCB THICKNESS: CHARTED ON SHEET 1
2. ALL DIMENSIONS ARE IN 'MM [INCH]'
3. LED'S CHARACTERISTICS:
 - 3.1 POWER DISSIPATION: 80mW MAX
 - 3.2 FORWARD CURRENT: 30mA MAX.
 - 3.3 FORWARD VOLTAGE: 2.2 VOLTS TYPICAL
 - 3.4 REVERSE VOLTAGE: 5.0 VOLTS MAX.
 - 3.5 PEAK EMISSION WAVELENGTH: GREEN LED 565 nm TYPICAL, YELLOW LED 590 nm TYPICAL
 - 3.6 ANODE \rightarrow CATHODE
 - 3.7 SINGLE GREEN COLOR AND BI-COLOR GREEN HAVE SAME POLARITY

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
TOP VIEW (COMPONENT SIDE)

X.±	X°.±	UNITS	NAME (INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO., LTD. TAIPEI, TAIWAN, R.O.C.
.X ± 0.10 [0.004]	.X°.±	MM [INCH]	CUSTOMER	
.XX ± 0.080 [0.003]	.XX°.±	MAT'L	PART NO. (INTENDED USE)	TITLE:
.XXX ±	.XXX°.±	FINISH	JFM38A1A-013*-4N	2X1 RJ45 GIGABIT CONNECTOR
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Q'TY			CHKD: Z.H. Xu 10/5'04	305-0000-1282
			DR: Z.C Zhang 10/5'04	SCALE SHEET REV.
				N/A 2/5 X1



ELECTRICAL SPECIFICATIONS @ 25° unless otherwise noted:

INDUCTANCE:	400uH min., 100kHz, 0.1Vrms, 8mA DC, J1-J2, J3-J6, J4-J5, J7-J8, Lp.
DIELECTRIC RATING:	1500Vrms, 1 minute tested between P(2-13) to J(1-8) and between P(14-19,21-26) to J(1-8)
TURNS RATIO & POLARITY:	Per schematic.
INSERTION LOSS:	-1.2dB max., 1MHz - 100MHz.
RETURN LOSS:	-18dB min., 1MHz - 30MHz. -15dB min., 30MHz - 60MHz. -12dB min., 60MHz - 80MHz. -10dB min., 80MHz - 100MHz.
CROSSTALK:	-45dB min., 1MHz - 30MHz. -40dB min., 30MHz - 60MHz. -37dB min., 60MHz - 80MHz. -35dB min., 80MHz - 100MHz.
COMMON MODE REJECTION:	-45dB min., 1MHz - 30MHz. -40dB min., 30MHz - 60MHz. -37dB min., 60MHz - 80MHz. -35dB min., 80MHz - 100MHz.
OPERATING TEMPERATURE RANGE:	0°C to +70°C.

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.X±	.X°±	MAT'L	CUSTOMER	
.XX±	.XX°±	FINISH	PART NO.(INTENDED USE)	TITLE:
.XXX±	.XXX°±		JFM38A1A-013*-4N	2X1 RJ45 GIGABIT CONNECTOR
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Q'TY			CHKD: Z.H. Xu 10/5'04	305-0000-1282
			DR: Z.C. Zhang 10/5'04	SCALE SHEET REV.
				N/A 3/5 X1

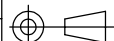
SPECIFICATIONS:

1. ELECTRICAL:

- 1.1 CURRENT RATING: 1.5 AMPERES MAXIMUM
- 1.2 VOLTAGE RATING: 150 VAC
- 1.3 DIELECTRIC WITHSTAND VOLTAGE: 1500 VAC ACROSS TRANSFORMER

2. MECHANICAL:

- 2.1 MATING FORCE: 4 LBS MAXIMUM WITH LATCH DEPRESSED
- 2.2 DURABILITY (MATING/UNMATING): 1000 CYCLES
- 2.3 OPERATING TEMP: 0 TO 70 DEG C
- 2.4 INSERTION FORCE OF PCB RETENTION POSTS: 8.5 LBS MAXIMUM
- 2.5 FLAMMABILITY: UL 94 V-0

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.XX±	.XX°.±	FINISH	PART NO.(INTENDED USE)	TITLE: 2X1 RJ45 GIGABIT CONNECTOR						
.XXX±	.XXX°.±		JFM38A1A-013*-4N	APPD: L.C WU 10/5'04	DWG NO.: 305-0000-1282					
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			SCALE		SHEET	REV.				
			N/A		4/5	X1				
DR: Z.C Zhang 10/5'04										

ITEM	DESC	Q' TY	MATERIAL	TREATMENT	REMARKS
1	HOUSING	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	MOLDED BLACK	
2	CONTACT	16/26	PHOSPHOR BRONZE	50 μ MIN GOLD AT CONTACT AREA 100 μ TIN/LEAD AT SOLDERING AREA 50 - 120 μ NICKEL UNDERPLATING	
3	SHIELD	1	BRASS ALLOY	50-120 μ TIN/LEAD OVER 50-120 μ NICKEL	
4	CAPACITOR	2		1000 pF 3 KV	
5	RESISTOR	4X2		75 OHMS	
6	PCB	3	FR4	NONE	TOP BOARD INCLUDES CAPACITORS & RESISTORS
7	LED	4		GREEN X2 YELLOW / GREEN X2	
8	MAGNETICS	2			
9	GND PLATE	1	BRASS ALLOY	50-120 μ TIN/LEAD OVER 50-120 μ NICKEL	
10	GROUND CONTACT	1	BRASS ALLOY	100-200 μ TIN/LEAD OVER 50-100 μ NICKEL	

REMARK:

JFM
SERIES PREFIX
JFM=JACK WITH MAGNETIC

3 8 A
CORE COUNT:
8=8 CORE
CONFIGURATION:
A=2X1
PROTOCOL TYPE:
3=10/100/1000 BASE T

1 A
PCB ATTACH METHOD
1=SOLDER TAIL

LEDs
A=GREEN LEDs
LEFT SIDE,
BI-COLOR
LEDs RIGHT SIDE

013*
EXTENSION CODE
4
SOFT TRAY

N
NONE

X.±	X°±	UNITS	NAME(INTENDED USE)	FOXCONN HON HAI PRECISION IND. CO.,LTD. TAIPEI, TAIWAN, R.O.C.
.X±	.X°±	MAT'L	CUSTOMER	
.XX±	.XX°±	FINISH	PART NO.(INTENDED USE)	TITLE:
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			DR: Z.C Zhang 10/5'04	DWG NO.: 305-0000-1282
				SCALE SHEET REV. N/A 5/5 X1

富士康(昆山)電腦接插件有限公司
Foxconn (Kun Shan) Computer Connector Co.,Ltd

實驗室檢測報告

Laboratory Test Report

報告日期 DATE : 3/16/2005

產品名稱 : 2x1 Gigabit

Part Name

料號 : JFM38A1A-0135-4N

Part No.

申請單位 : CID ME

Applicant

報告類別 : 信賴性 精密量測 其它測試

Report Type : Qualification Precision Measure Other Test

接收日期 : 1/18/2005

Receive Date

檢測日期 : 1/18/2005

Test Date

檢測人員 : 王衛娟

Tested by : Alva Wang

審核人員 :

Checked by

Weber Tian Mar.16.2005

核准人

Approved by

FOXCONN

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說明

ILLUSTRATION

1. 樣品標識與檢測報告編號一致。
Specimen mark is the same as Testing No.
2. 本報告僅對樣品有效,未經許可,不得部分复制。
The report only valid & responsible for specimen.
Copy or using separately are prohibited without permission.
3. 本報告共 11 頁,分離使用無效。
The report contains 11 page(s) , invalid when used separately.

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1.SCOPE

1.1 APPLICANT: MUKB14

1.2 TESTED SAMPLES: 15 PCS

1.3 PURPOSE

This qualification test report contains the quality requirements, test procedures and test results of a qualification test program on the FOXCONN'S PRODUCT JFM38A1A-0135-4N.

2.APPLICABLE DOCUMENTS

EIA-364& MIL-STD-202G
Product specification

Test method for electrical components
EB5-ASJF-023 Rev. A

3.TEST SEQUENCE

3.1 TEST CONDITIONS

Unless otherwise specified, tests and examinations are conducted under conditions within the following ranges:

Temperature: 15~35°C

Atmospheric pressure: 550 to 800 millimeters (25.6 to 31.5 inches) of Mercury

Relative Humidity: 20~80%

3.2 QUALIFICATION TEST SEQUENCE

ITEM	TEST DESCRIPTION	TEST SEQUENCE							TEST METHOD
		A	B	C	D	E	F	G	
1	EXAMINATION OF PRODUCT	1,11	1,11	1,13	1,4	1,13	1,7	1,6	4-1
2	CONTACT RESISTANCE	2,6	2,6	2,6		2,6			4-2
3	INSULATION RESISTANCE			7		7			4-3
4	DWV CONTACT OT CONTACT			8		8			4-4
5	DWV ACROSS ALL TRANSFORMERS							4	4-5
6	NEAR AND CROSSTALK	7	7	9		9	2		4-6
7	INSERTION LOSS	8	8	10		10	3		4-7
8	RETURN LOSS	9	9	11		11	4		4-8
9	DIFF. TO COMMON MODE REJECTION	10	10	12		12	5		4-9
10	INDUCTANCE						6		4-10
11	VIBRATION		4						4-11
12	PRE-CONDITION 50 CYCLES	3,5	3,5	3,5		3,5			4-12
13	INSERTION FORCE TO PCB				2				4-13
14	JACK RETENTIN FORCE				3				4-14
15	TEMPERATURE LIFE	4							4-15
16	THERMAL SHOCK			4					4-16
17	TEMPERATURE HUMIDITY CYCLING					4			4-17
18	SOLDERABILITY							3	4-18
19	RESISTANCE TO SOLDERING HEAT							2	4-19
20	RESIST TO SOLVENT MARKING PERM							5	4-20
	SAMPLES SIZE PER TEST GROUP	2	2	2	2	2	3	2	

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4. TEST METHOD OF INSPECTION

4-1 EXAMINATION OF PRODUCT

The test is performed in accordance with EIA-364-18A. Visual inspection in compliance with applicable specifications and documents were performed. The test samples shall be free from defects such as damage, creep, deformation, blister and burrs that are detrimental to the functions and appearances of test samples.

4-2 CONTACT RESISTANCE

The test is performed in accordance with EIA-364-23A. Open circuit voltage shall not exceed 20mV while test current of 100mA is applied. Test : J1-J2, J3-J6, J4-J5, J7-J8.

4-3 INSULATION RESISTANCE

The test is performed in accordance with EIA-364-21C. Insulation resistance is measured between adjacent contacts after applying 500V DC for 1 minute on unmated connectors.

4-4 DWV CONTACT TO CONTACT

The test is performed in accordance with EIA-364-20B. A 1000 V DC is applied between two adjacent contacts to contacts of the test samples for 60 seconds, when applying the voltage, the leakage current is monitored and shall be 1mA.

4-5 DWV ACROSS ALL TRANSFORMERS

The test is performed in accordance with EIA-364-20B. A 1500 V AC for 60 seconds, when applying the voltage, the leakage current is monitored and shall be 1mA.

4-6 NEAR AND CROSSTALK

The test is performed in accordance with EIA-364-90.

4-7 INSERTION LOSS

The test is performed in accordance with EIA-364-101.

4-8 RETURN LOSS

The test is performed in accordance with EIA-364-108.

4-9 DIFF. TO COMMON MODE REJECTION

Input the common signal into one port of the sample, and receive the difference signal at the other port.

4-10 INDUCTANCE

Refer to customer drawing. Measure inductance at specified points. Test: J1-J2, J3-J6, P9-P5, P11-P7
Frequency: 100k Hz/100mV RMS, 8mA DC bias 350 μ H Min.

4-11 VIBRATION

The test is performed in accordance with EIA-364-28D. Condition V, level D, Random. mated pairs, 20 to 500Hz. No discontinuities > 1 microsecond when measured in accordance with EIA-364-46. No physical damage.

4-12 PRE-CONDITION 50 CYCLES

The test is performed in accordance with EIA-364-09C. 50 cycles @ 500 cycles/hour latch is depressed during cycling.

4-13 INSERTION FORCE TO PCB

Apply force perpendicular to PCB on top surface of jack at rate of 0.5 inch per minute.

Measure force to seat jack on to a 0.062 inch thick PCB.

Mounting holes must comply to customer drawing. The test rate was 12.7mm per minute.

4-14 JACK RETENTION FORCE

Apply force perpendicular to PCB on top surface of jack at rate of 12.7mm per min.

Measure force to pull jack out of a 0.062 inch thick PCB.

4-15 TEMPERATURE LIFE

The test was performed in accordance with EIA-364-17B, test condition 3. Temperature: 85-2°C, duration 1000 hours.

4-16 THERMAL SHOCK

The test is performed in accordance with EIA-364-32C. The test samples are exposed with following test condition: -40°C for 20 minutes and +70°C for 20 minutes for 5 cycles. There is a 5 minutes maximum transition time between two extreme temperature.

4-17 TEMPERATURE-HUMIDITY CYCLING

The test is performed in accordance with EIA-364-31B, method III, condition C. The test samples are exposed to 25°C~65°C temperature, 93% (RH) humidity for 10 cycles, total 240 hours.

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4-18 SOLDERABILITY

The test is performed in accordance with MIL-STD-202G, method 208H. After completion of the steam aging exposure for 8 hours, the test samples shall be air-dried at room ambient. Solderability testing shall be performed within 72 hours of the specified aging exposure. The termination ends shall be at least covered by a continuous new solder coating. Pin holes or voids shall not be concentrated in one area, and shall not exceed 5 percent of the total area.

4-19 RESISTANCE TO SOLDERING HEAT

Comply with method EIA-364-56A on mated connectors. The distance between the mounting surface and solder surface shall be 1 mm to 2.54mm. The fused solder temperature shall be 260±5°C. The dipping time shall be 10±1 seconds. The leaving time shall be 1 hour.

4-20 RESIST TO SOLVENT MARKING PERM

The test was performed in accordance with method EIA-364-11A, group 1, chemical D.
No physical damage to components. Marking must remain legible.

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5. THE SUMMARY OF THE TEST RESULTS**GROUP "A"**

TEST DESCRIPTION		REQUIREMENT	RESULT			RATE
1. VISUAL EXAMINATION		All components shall be properly assembled and free of burrs, warpages, scratches, broken chips, and others abnormalities.	Pass the specified requirement			Pass
2. CONTACT RESISTANCE		60m Ω Max.	Max. 42.00	Min. 18.10	Avg. 28.70	Pass
			Unit: m Ω			
3. PRE-CONDITION 50 CYCLES		After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
4. TEMPERATURE LIFE		Upon completion of the test, there shall be no physical damage to the samples and the samples shall pass the requirements of following test items.	See the following test items			/
5. PRE-CONDITION 50 CYCLES		After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
6. CONTACT RESISTANCE		No change greater than 10m Ω Max.	Max. 5.20	Min. -1.36	Avg. 1.32	Pass
			Unit: m Ω			
7. CROSSTALK		Frequency	Spec		Pass the specified requirement	Pass
		1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
8. INSERTION LOSS					Pass the specified requirement	Pass
TX	1MHz~100MHz	-1.2dB(Min.)				
	RX	1MHz~100MHz	-1.2dB(Min.)			
TX	1MHz~30MHz	-18dB(Max.)				
	30MHz~60MHz	-15dB(Max.)				
	60MHz~80MHz	-127dB(Max.)				
	80MHz~100MHz	-10dB(Max.)				
RX	1MHz~30MHz	-18dB(Max.)				
	30MHz~60MHz	-15dB(Max.)				
	60MHz~80MHz	-127dB(Max.)				
	80MHz~100MHz	-10dB(Max.)				
10. DCMR	TX	1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
	RX	1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
11. VISUAL EXAMINATION		All components shall be properly assembled and free of burrs, warpages, scratches, broken chips, and others abnormalities.	Pass the specified requirement			Pass

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GROUP "B"

TEST DESCRIPTION		REQUIREMENT	RESULT			RATE
1.VISUAL EXAMINATION		All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement			Pass
2. CONTACT RESISTANCE		60m Ω Max.	Max. 39.28	Min. 18.18	Avg. 27.70	Pass
			Unit: m Ω			
3.PRE-CONDITION 50 CYCLES		After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
4.VIBRATION		No electrical discontinuity greater than 1 microsecond during the test. No physical damage.	Pass the specified requirement			Pass
5.PRE-CONDITION 50 CYCLES		After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
6. CONTACT RESISTANCE		No change greater than 10m Ω Max.	Max. 1.42	Min. -0.62	Avg. 0.28	Pass
			Unit: m Ω			
7.CROSSTALK		Frequency	Spec			
		1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
8.INSERTION LOSS	TX	1MHz~100MHz	-1.2dB(Min.)			
	RX	1MHz~100MHz	-1.2dB(Min.)			
9.RETURN LOSS	TX	1MHz~30MHz	-18dB(Max.)		Pass the specified requirement	Pass
		30MHz~60MHz	-15dB(Max.)			
		60MHz~80MHz	-127dB(Max.)			
		80MHz~100MHz	-10dB(Max.)			
	RX	1MHz~30MHz	-18dB(Max.)			
		30MHz~60MHz	-15dB(Max.)			
		60MHz~80MHz	-127dB(Max.)			
		80MHz~100MHz	-10dB(Max.)			
10.DCMR	TX	1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
	RX	1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
11.VISUAL EXAMINATION		All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement			Pass

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GROUP "C"

TEST DESCRIPTION		REQUIREMENT	RESULT			RATE
1.VISUAL EXAMINATION		All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement			Pass
2. CONTACT RESISTANCE		60m Ω Max.	Max. 40.02	Min. 18.33	Avg. 28.02	Pass
			Unit: m Ω			
3.PRE-CONDITION 50 CYCLES		After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
4.THERMAL SHOCK		Upon completion of the test, there shall be no physical damage to the samples and the samples shall pass the requirements of following test items.	See the following test items			/
5.PRE-CONDITION 50 CYCLES		After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
6. CONTACT RESISTANCE		No change greater than 10m Ω Max.	Max. 1.32	Min. -0.74	Avg. 0.31	Pass
			Unit: m Ω			
7.INSULATION RESISTANCE		500M Ω Min.	> 5 $\times 10^4$ M Ω			Pass
8.DIELECTRIC WITHSTANDING VOLTAGE		No evidence of breakdown or flash burn. No burn caused by short circuit. No insulation destruction. Leakage current: 1mA.	Pass the specified requirement			Pass
9.CROSSTALK		Frequency	Spec		Pass the specified requirement	Pass
		1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
10.INSERTION LOSS	TX	1MHz~100MHz	-1.2dB(Min.)		Pass the specified requirement	Pass
	RX	1MHz~100MHz	-1.2dB(Min.)			
11.RETURN LOSS	TX	1MHz~30MHz	-18dB(Max.)			
		30MHz~60MHz	-15dB(Max.)			
		60MHz~80MHz	-127dB(Max.)			
		80MHz~100MHz	-10dB(Max.)			
	RX	1MHz~30MHz	-18dB(Max.)			
		30MHz~60MHz	-15dB(Max.)			
		60MHz~80MHz	-127dB(Max.)			
		80MHz~100MHz	-10dB(Max.)			
12.DCMR	TX	1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
	RX	1MHz~30MHz	-45dB(Max.)			
		30MHz~60MHz	-40dB(Max.)			
		60MHz~80MHz	-37dB(Max.)			
		80MHz~100MHz	-35dB(Max.)			
13.VISUAL EXAMINATION		All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement			Pass

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GROUP "D"

TEST DESCRIPTION	REQUIREMENT	RESULT		RATE
1.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement		Pass
2.INSERTION FORCE TO PCB	15lbs Max.	Sample 1	Sample2	Pass
		0.13	0.01	
		Unit: lbs		
3.JACK RETENTION FORCE	1lbs Min.	Sample 1	Sample2	Pass
		1.15	1.73	
		Unit: lbs		
4.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement		Pass

GROUP "E"

TEST DESCRIPTION	REQUIREMENT	RESULT			RATE
1.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement			Pass
2. CONTACT RESISTANCE	60m Ω Max.	Max.	Min.	Avg.	Pass
		40.67	17.72	28.00	
		Unit: m Ω			
3.PRE-CONDITION 50 CYCLES	After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
4.TEMPERATURE HUMIDITY CYCLING	Upon completion of the test, there shall be no physical damage to the samples and the samples shall pass the requirements of following test items.	See the following test items			/
5.PRE-CONDITION 50 CYCLES	After 50 cycles of durability test the samples shall pass the requirements of the following test items	See the following items			/
6. CONTACT RESISTANCE	No change greater than 10m Ω Max.	Max.	Min.	Avg.	Pass
		0.94	0.04	0.37	
		Unit: m Ω			
7.INSULATION RESISTANCE	500M Ω Min.	> 5 $\times 10^4$ M Ω			Pass
8.DIELECTRIC WITHSTANDING VOLTAGE	No evidence of breakdown or flash burn. No burn caused by short circuit. No insulation destruction. Leakage current: 1mA.	Pass the specified requirement			Pass

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9.CROSSTALK	Frequency		Spec	Pass the specified requirement	Pass
	1MHz~30MHz		-45dB(Max.)		
	30MHz~60MHz		-40dB(Max.)		
	60MHz~80MHz		-37dB(Max.)		
80MHz~100MHz		-35dB(Max.)			
10.INSERTION LOSS	TX	1MHz~100MHz -1.2dB(Min.)			
	RX	1MHz~100MHz -1.2dB(Min.)			
11.RETURN LOSS	TX	1MHz~30MHz -18dB(Max.)			
		30MHz~60MHz -15dB(Max.)			
		60MHz~80MHz -127dB(Max.)			
		80MHz~100MHz -10dB(Max.)			
	RX	1MHz~30MHz -18dB(Max.)			
		30MHz~60MHz -15dB(Max.)			
		60MHz~80MHz -127dB(Max.)			
		80MHz~100MHz -10dB(Max.)			
12.DCMR	TX	1MHz~30MHz -45dB(Max.)			
		30MHz~60MHz -40dB(Max.)			
		60MHz~80MHz -37dB(Max.)			
		80MHz~100MHz -35dB(Max.)			
	RX	1MHz~30MHz -45dB(Max.)			
		30MHz~60MHz -40dB(Max.)			
		60MHz~80MHz -37dB(Max.)			
		80MHz~100MHz -35dB(Max.)			
13.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.		Pass the specified requirement	Pass	

GROUP "F"

TEST DESCRIPTION	REQUIREMENT	RESULT	RATE	
1.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement	Pass	
2.CROSSTALK	Frequency		Pass the specified requirement	
	1MHz~30MHz			-45dB(Max.)
	30MHz~60MHz			-40dB(Max.)
	60MHz~80MHz			-37dB(Max.)
80MHz~100MHz		-35dB(Max.)		
3.INSERTION LOSS	TX	1MHz~100MHz -1.2dB(Min.)		
	RX	1MHz~100MHz -1.2dB(Min.)		
4.RETURN LOSS	TX	1MHz~30MHz -18dB(Max.)		
		30MHz~60MHz -15dB(Max.)		
		60MHz~80MHz -127dB(Max.)		
		80MHz~100MHz -10dB(Max.)		
	RX	1MHz~30MHz -18dB(Max.)		
		30MHz~60MHz -15dB(Max.)		
		60MHz~80MHz -127dB(Max.)		
		80MHz~100MHz -10dB(Max.)		

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5.DCMR	TX	1MHz~30MHz	-45dB(Max.)							Pass
		30MHz~60MHz	-40dB(Max.)							
		60MHz~80MHz	-37dB(Max.)							
		80MHz~100MHz	-35dB(Max.)							
	RX	1MHz~30MHz	-45dB(Max.)							
		30MHz~60MHz	-40dB(Max.)							
		60MHz~80MHz	-37dB(Max.)							
		80MHz~100MHz	-35dB(Max.)							
6.INDUCTANCE (μ H)	Frequency	Spec	Test pin	Sample1		Sample2		Sample3		Pass
				upper	lower	upper	lower	upper	lower	
	100KHz	400 μ H(Min.)	J1-J2	585.74	594.71	629.22	596.74	624.15	697.73	
	100KHz	400 μ H(Min.)	J3-J6	627.73	621.57	638.78	612.06	618.70	595.18	
	100KHz	400 μ H(Min.)	J4-J5	673.17	566.51	685.06	637.70	643.35	704.68	
100KHz	400 μ H(Min.)	J7-J8	628.12	705.93	644.03	591.48	604.15	611.61		
7.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.			Pass the specified requirement						Pass

GROUP "G"

TEST DESCRIPTION	REQUIREMENT	RESULT	RATE
1.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement	Pass
2.SOLDERABILITY-WETTING BALANCE	No physical damage.	Pass the specified requirement	Pass
3.SOLDERABILTIY	Finish to be free of contaminants and no solder defects.	Pass the specified requirement	Pass
4.DWV ACROSS ALL TRANSFORMERS	No evidence of arcing or breakdown.	Pass the specified requirement	Pass
5.RESIST TO SOLVENT MARKING PERM	No physical damage to components. Marking must remain legible.	Pass the specified requirement	Pass
6.VISUAL EXAMINATION	All components shall be properly assembled and free of burrs, warpages,scratches,broken chips, and others abnormalities.	Pass the specified requirement	Pass

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